

Processing/Physical Characteristics	dry / cond	Unit	Test Standard
ISO Data			
^[C] Molding shrinkage, parallel	1.0 / *	%	ISO 294-4, 2577
^[C] Molding shrinkage, normal	0.8 / *	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Tensile Modulus	3700 / 1300	MPa	ISO 527
^[C] Yield stress	75 / -	MPa	ISO 527
^[C] Yield strain	4 / -	%	ISO 527
Flexural modulus, 23°C	3200 / 1100	MPa	ISO 178
Flexural strength	105 / 50	MPa	ISO 178
^[C] Charpy impact strength, +23°C	85 / -	kJ/m ²	ISO 179/1eU
^[C] Charpy notched impact strength, +23°C	4.5 / 16	kJ/m ²	ISO 179/1eA

[C]: CAMPUS

Thermal properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Melting temperature, 10°C/min	257 / *	°C	ISO 11357-1/-3
^[C] Temp. of deflection under load, 1.80 MPa	60 / *	°C	ISO 75-1/-2
^[C] Temp. of deflection under load, 0.45 MPa	200 / *	°C	ISO 75-1/-2
^[C] Burning Behav. at 1.5 mm nom. thickn.	V-0 / *	class	IEC 60695-11-10
Yellow Card available	yes / *	-	-
^[C] Burning Behav. at thickness h	V-0 / *	class	IEC 60695-11-10
Thickness tested	0.8 / *	mm	-

[C]: CAMPUS

Electrical properties	dry / cond	Unit	Test Standard
ISO Data			
^[C] Volume resistivity	1E13 / -	Ohm*m	IEC 62631-3-1
^[C] Surface resistivity	* / 1E15	Ohm	IEC 62631-3-2
^[C] Electric strength	34 / -	kV/mm	IEC 60243-1
^[C] Comparative tracking index	600 / -	-	IEC 60112

[C]: CAMPUS

Other properties	dry / cond	Unit	Test Standard
^[C] Density	1160 / -	kg/m ³	ISO 1183

[C]: CAMPUS

Characteristics

Processing

Injection Molding

Applications

Electrical and Electronical

Special Characteristics

Flame retardant, Halogen-free